

## Spring Probe CCC – Measurements & Simulations

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# TestConX 2025

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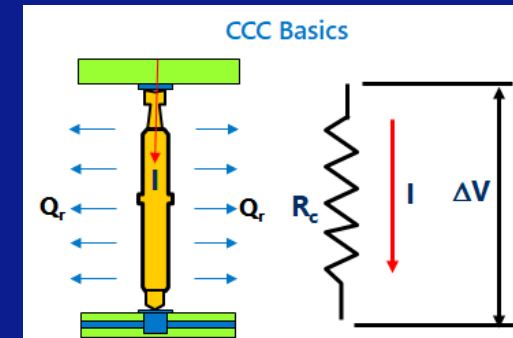
Spring Probe CCC – Measurements & Simulations

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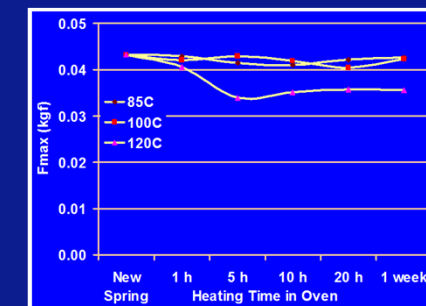
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## Current Carrying Capacity (CCC) Physics

- Current Carrying Capacity (CCC) definition
  - Refer to probe or other contact's capability of maximum current going through without causing damages or deteriorating performance due to temperature raise caused by heat.
- CCC physical phenomenon
  - Electric current going through probe or any contacts will generate heat due to electric resistance in probe/contacts.
  - Heat generated from electric current will be released to environment through probe/contact house.
  - Heat generated can cause probe/contact temperature rise in probe/contact that will reach steady state or equilibrium to released heat.
- Spring probe/contact failure modes
  - Major failure is spring or contact relaxation or degradation due to losing enough compression force.



### Spring Relaxation vs Temperature



## Current Carrying Capacity (CCC) Physics

- Probe/Contact temperature raise calculation
  - Total power generated when current  $I$  going through probe

$$P = I^2 \times R_c$$

- $R_c$  refers to total electric resistance ( $R_{cs}$ ) of probes, which include resistances by material and contact surfaces
- Heat generated in probe,  $Q_g$ , & released to environment,  $Q_r$

$$Q_g \sim P$$

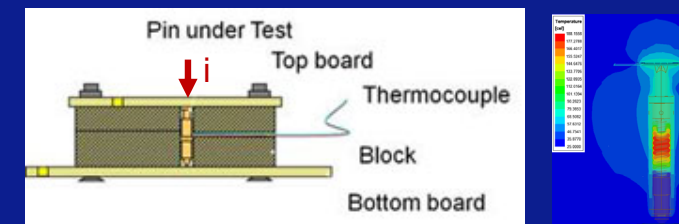
$$Q_r \sim \text{Heat transfer capacity}$$

- Temperature raise caused by heat.

$$\Delta T \propto (Q_g - Q_r)$$

- Major factors impacting probe temperature raises
  - Current going through probes, steady or pulse currents
  - Probe  $R_{cs}$
  - Heat releasing environment, such as socket structure, material & external heat transfer efficiency

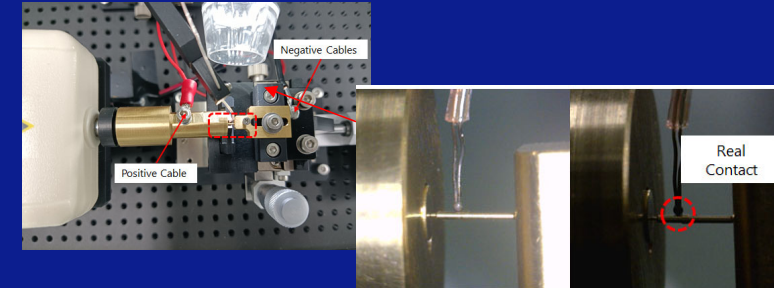
Probe, Current & Temperature Raise



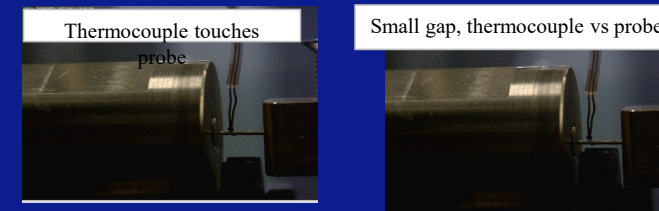
## CCC Measurement Methodologies

- Thermocouple methods
  - Thermocouple measures probe temperature by touching the probe body; probe is exposed in still air
- Factors affecting measurement accuracy
  - Reliable contact of thermocouple to probe/contact body
  - Heat transfer environment, such as air flow
- Limitations on thermocouple methods
  - Thermocouple contact status on CCC results
    - Keep thermocouple touching probe tightly as required in CCC test
    - T-rise drops if any small gap of thermocouple tip to probe
  - Differences from probe/contact usage environments
    - Probe/contact houses big impacts on heat transfer, such as structure and materials, etc.
    - Many more probes/contacts in one test socket or interposer

Thermocouple Method: probe in still air



Impacts of thermocouple contacts on probe CCC



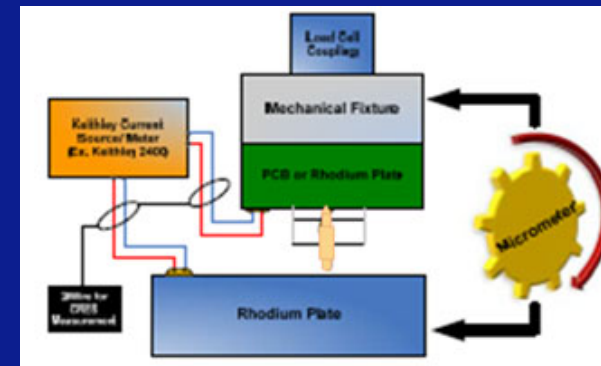
Current(A)	Touching	Gap
	T_raise	T_raise
1	24.6	18.8
2	57.9	45.8
3	105.2	79.1

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## CCC Measurement Methodologies

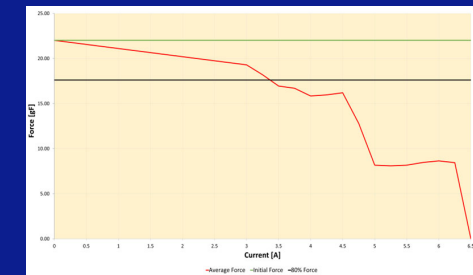
- Force Gauge methods (ISMI)
  - Standard CCC measurement method on probe card technologies by ISMI.
  - Criteria: 20% spring force permanent reduction as current applied.
  - Apply current (2 mins), measure spring probe force
  - Repeat these steps and take current reading when force drops to 80%.
- Pro & con of ISMI methods
  - Measured probe in socket house.
  - Measurements have more uncertainty since spring force generally has more variations, +/-20%
  - ISMI method is mostly developed for contacts with solid piece configuration, such as single wire contact.

ISMI Method



“ISMI CCC Measurement Standard”, E Boyd Daniels, IEEE Test Workshop” 2009

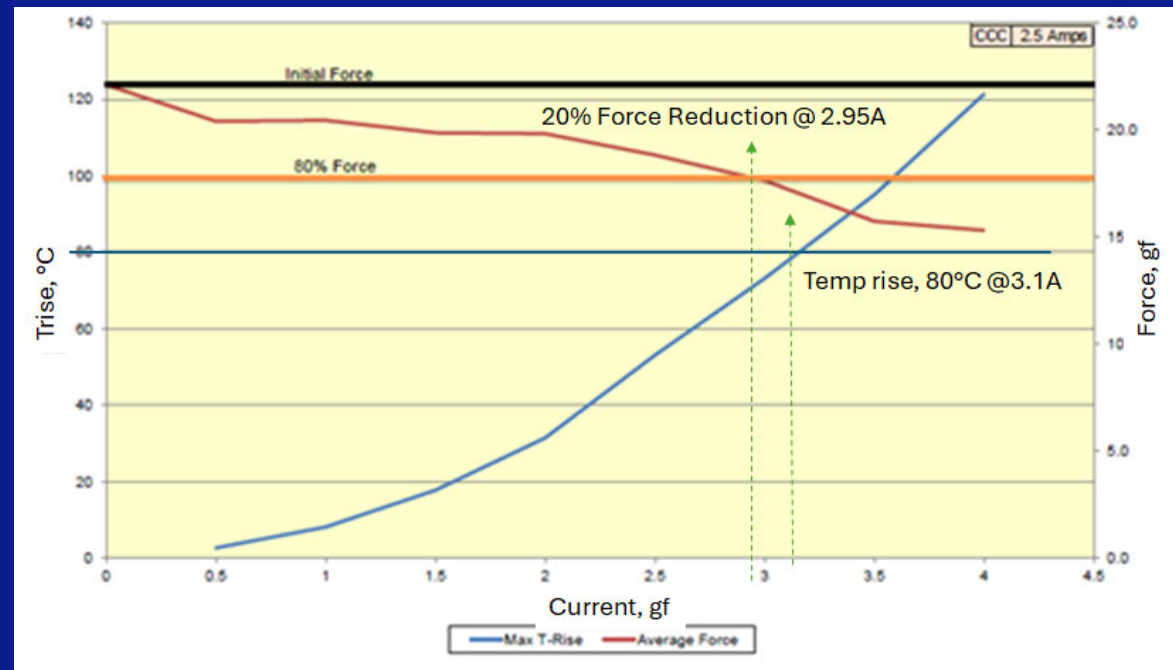
CCC Measurement Example per ISMI Method



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## Example of DC CCC Measurements Results

- CCC with both methodologies to get similar results.

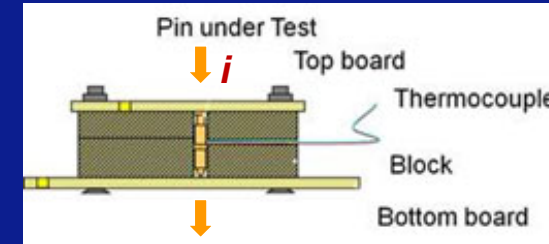


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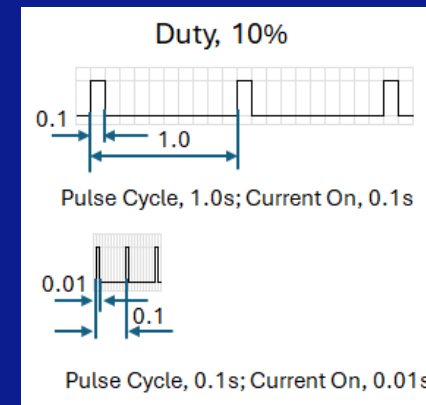
## Major Factors Impacting Contacts CCC

- DC current
  - Depends on amount current going through probes
- Pulse current
  - Pulse current Duty%,
    - $Duty\% = \Delta_{on}/\Delta_t$
    - $\Delta_{on}$ : time of current going through
    - $\Delta_t$ : total time in one pulse
  - Amount of current
  - Time of current on
    - 10% duty:  $\frac{0.1s}{1.0s}$  vs  $\frac{0.01s}{0.1s}$  vs  $\frac{0.001s}{0.01s}$
    - 50% duty:  $\frac{0.5s}{1.0s}$  vs  $\frac{0.05s}{0.1s}$  vs  $\frac{0.005s}{0.01s}$
- Socket & teat transfer environment
  - Socket material & structure
  - External heat transfer, such as still air or flow air

### Current Through Probe



### Pulse Current Variation

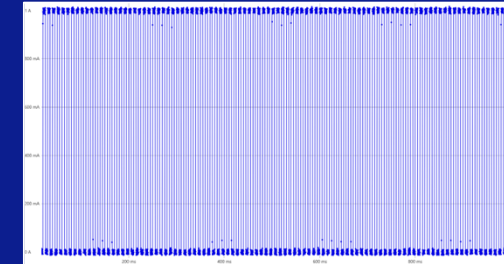
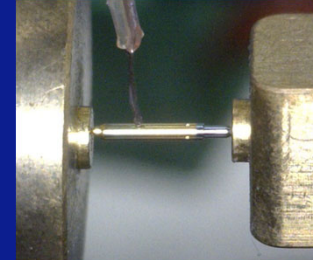


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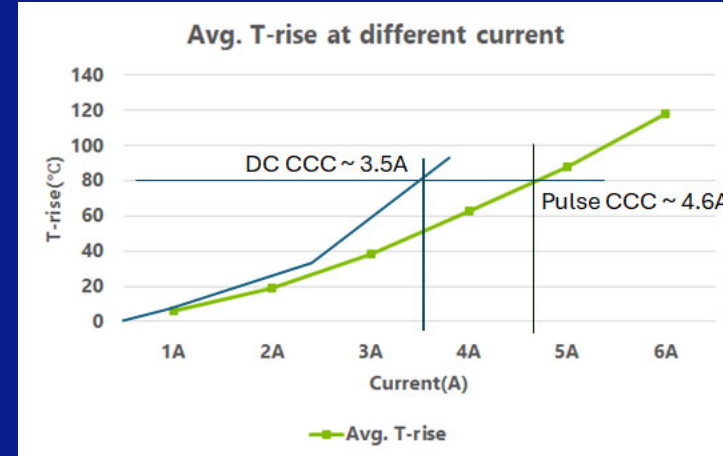
## Pulse Current Measurement Example

### Pulse Current Test Set up

- Measurement Setting
  - Duty cycles: 50%
  - Pulse current: 1A,2A,3A,4A,5A,6A
  - Duration time: 100s to reach steady state
  - Pulse time: 0.005s
  - Off time: 0.005s
- Measurement Results
  - Pulse CCC @ 80°C Trise: ~ 4.6A
  - DC CCC @ 80°C Trise: ~ 3.5A



### Pulse Current CCC Results



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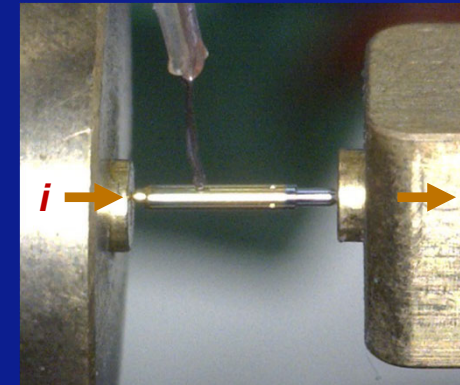
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## Thermal Simulations on Probe CCC

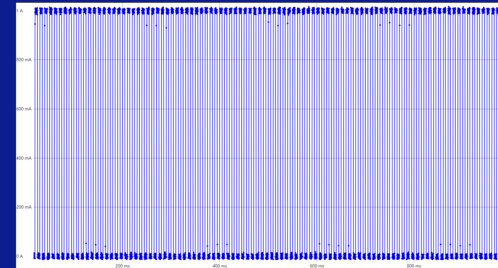
- Why CCC Simulation
  - Avoid limitations on measurements
    - Differences of lab set up vs end use environments
    - Contacts & house structure
    - Multi factors in setup to affect CCC results
    - Complexity of measurements for pulse currents
  - Quick responses to customer demands
  - Predict CCC when developing new contact configuration
  - Able to simulate extra high temperature environment, which is hard to achieve in lab measurements
- Boundary conditions
  - Ambient Temperature in Chamber is considered at 23°C
  - $T_{\text{Rise}} = \text{Measured Temperature} - \text{Ambient Temperature}$
  - Simulating for steady state analysis.
  - Following Material Properties are considered for respective Material

Spring Probe in Air

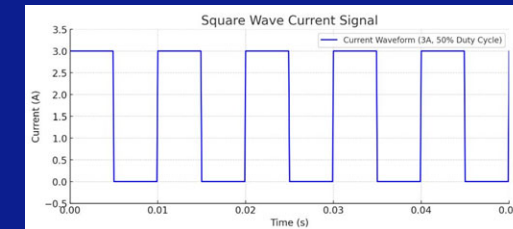


## Thermal Simulations on Probe Pulse CCC

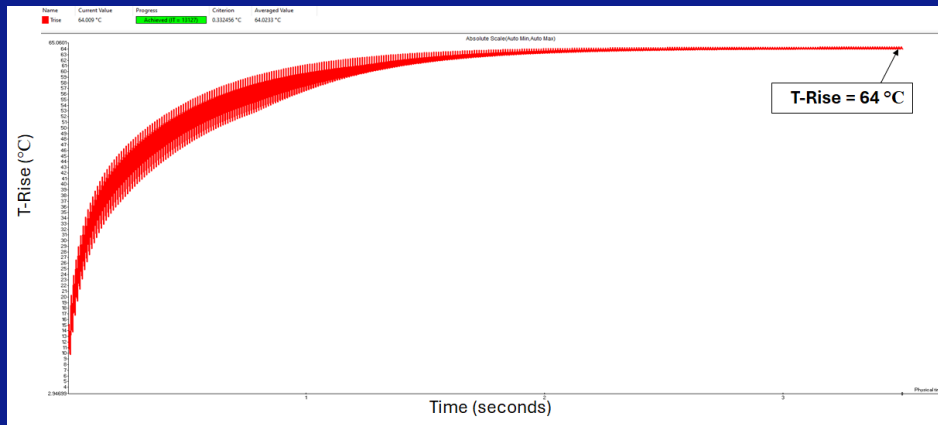
- Pulse CCC simulation
  - Pulse current: 1 ~ 6A
  - Duty time: 50%
  - Width: 0.005s
  - Off time: 0.005s



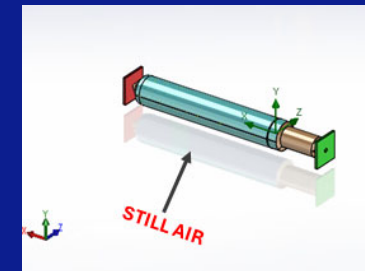
Pulse Current (example)



### Temperature Rise to Steady Status



### Simulations Model

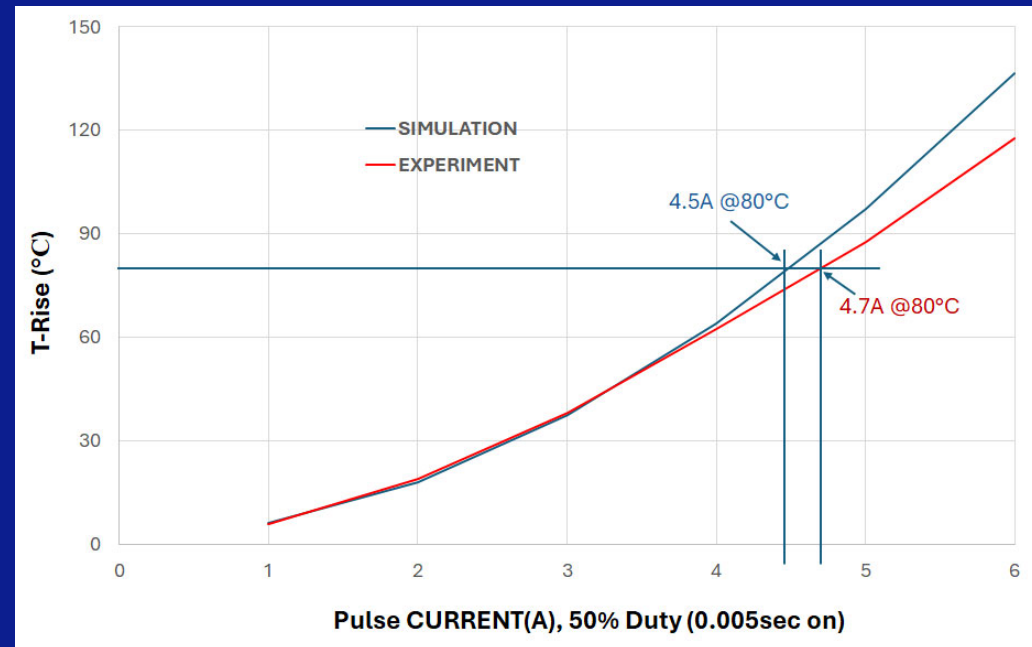


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## Thermal Simulations on Probe Pulse CCC

- Simulations vs Experiment Results:
  - Simulation, 4.5A @80°C
  - Experiment: 4.7A @ 80°C

Pulse CCC, Simulations vs Experimental



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## Summary

- Physics of contact CCC follows basic heat transfer principles.
- Contacts CCC are affected by various factors
  - Currents going through contact, DC or pulse current
  - Contact structure and materials
  - Measurement methodologies have impacts on CCC results
- Thermal simulations on heat transfer can be applied to predict CCC



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